

## AMENDMENTS TO THE CLAIMS

### Listing Of Claims

Claims 1-56 (Canceled)

57. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe; and

a plastic body comprising a first ~~polymer~~ member comprising a first compound encapsulating the die and a portion of the leadframe, and a second ~~polymer~~ member comprising a second compound encapsulating the first ~~polymer~~ member;

the first member and the second member having geometries selected to reduce thermo-mechanical stresses in the package,

the first compound and the second compound having at least one filler selected to provide desired mechanical and electrical characteristics in the package.

~~, the first polymer member comprising a molded material and at least one filler, the first polymer member, the molded material and the filler configured to reduce thermo-mechanical stresses in the package.~~

58. (currently amended) The semiconductor package of claim 57 wherein the first member has a geometry selected to equalize volumes of the second compound on either side of the leadframe.

~~molded material comprises a cured molding compound.~~

Claim 59. (canceled)

60. (currently amended) The semiconductor package of claim 57 58 wherein the first member and the second member comprise an epoxy.

~~second polymer member comprises a second filler.~~

61. (currently amended) The semiconductor package of claim 57 wherein the first member comprises a first filler and the second member comprises a second filler.

~~first polymer member has a selected geometry.~~

62. (currently amended) The semiconductor package of claim 57 wherein the first ~~polymer~~ member includes a filler selected to increase a strength of the package.

~~has selected dimensions.~~

63. (currently amended) The semiconductor package of claim 57 wherein the die includes wire bonds and the first ~~polymer~~ member encapsulates the wire bonds.

64. (currently amended) The semiconductor package of claim 57 wherein a package bow measured from a theoretical flat profile FP is less than about 3 mils.

~~the first polymer member and the second polymer member comprise a molding compound containing a filler.~~

65. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe;

~~a plurality of wire bonds bonded to the die and the leadframe,~~

a first ~~polymer~~ member encapsulating the die ~~and~~  
~~the wire bonds~~, and at least a portion of the leadframe;  
and

a second ~~polymer~~ member encapsulating the first  
~~polymer~~ member having substantially equal volumes of a  
molding compound on either side of the leadframe;

the first ~~polymer~~ member ~~comprising a rigid~~  
~~molded material~~ having a selected geometry for providing  
the substantially equal volumes and ~~at least one filler~~  
~~configured for reducing~~ ~~reduce~~ thermo-mechanical stresses  
in during molding of the second polymer member.

66. (currently amended) The semiconductor package of  
claim 65 wherein the first member and the second member  
comprise epoxy.

~~the selected geometry provides substantially equal~~  
~~volumes of a molding compound of the second polymer member~~  
~~on either side of the leadframe.~~

67. (currently amended) The semiconductor package of  
claim 65 wherein the first member includes a filler ~~is~~  
configured to increase a rigidity of the first ~~polymer~~  
member.

68. (currently amended) The semiconductor package of  
claim 65 wherein the first member ~~selected geometry~~ is  
configured to reduce a package bow measured from a  
theoretical flat profile FP to less than about 3 mils.

~~or warpage.~~

69. (currently amended) The semiconductor package of claim 65 wherein the first member and the second polymer member each include a filler.

~~comprises the rigid molded material.~~

70. (currently amended) The semiconductor package of claim 65 wherein the first ~~polymer~~ member and the second member comprise ~~s an~~ cured B-stage epoxy.

71. (currently amended) A semiconductor package comprising:

a leadframe having a first side and a second side;

a die on the leadframe;

~~a plurality of polymer members on the leadframe; and~~

a plastic body comprising a molding compound encapsulating the ~~polymer members~~ die and at least a portion of the leadframe, the plastic body having a first portion on the first side having a first volume and a second portion on the second side having a second volume;

~~the~~ a polymer member s on the leadframe having a selected ~~volume~~ geometry configured to equalize the first volume and the second volume and to reduce a package bow measured from a theoretical flat profile FP to less than about 3 mils.

~~thermo-mechanical stresses in the package during molding of the plastic body.~~

72. (currently amended) The semiconductor package of claim 71 wherein the polymer member ~~s~~ comprises a molding compound.

~~material selected from the group consisting of epoxy, silicone, room temperature vulcanizing (RTV) and polyimide.~~

73. (currently amended) The semiconductor package of claim 71 wherein the polymer member ~~is~~ comprises a tape material.

74. (currently amended) The semiconductor package of claim 71 wherein the polymer member ~~is~~ comprises a molding compound and a filler.

75. (currently amended) The semiconductor package of claim 71 ~~wherein the polymer~~ further comprising a plurality of polymer members are located on opposing sides of the die.

76. (currently amended) The semiconductor package of claim 71 wherein the ~~each~~ polymer member comprises a molded member.

~~has a generally rectangular shape.~~

77. (currently amended) The semiconductor package of claim 71 wherein the polymer member ~~is~~ comprises an electrically insulating cured material.

78. (currently amended) A semiconductor package comprising:

a leadframe;

a die on the leadframe;

~~a plurality of wire bonds bonded to the die and to the leadframe;~~

a ~~molded~~ first ~~polymer~~ member encapsulating the die ~~and the wire bonds~~ and a portion of the leadframe ~~and the first polymer member~~ comprising a first molding compound; and

~~and a first filler, the first polymer member, the first molding compound and the first filler configured to reduce thermo-mechanical stresses in the package; and~~

a molded second polymer member encapsulating the first polymer member, ~~the second polymer member~~ comprising a second molding compound on either side of the leadframe;

the first member and the second member having a geometry selected to reduce thermo-mechanical stresses in the package and to provide a package bow measured from a theoretical flat profile FP of less than about 3 mils.

~~the second polymer member comprising a second molding compound and a second filler.~~

79. (currently amended) The semiconductor package of claim 78 wherein the first molding compound and the second molding compound comprise an epoxy.

~~s a rigid plastic.~~

80. (currently amended) The semiconductor package of claim 78 wherein the second ~~polymer~~ member comprises substantially equal volumes of the second molding compound on either side of the leadframe.

81. (currently amended) The semiconductor package of claim 78 wherein the first ~~polymer~~ member includes at least one filler.

~~has a selected geometry and selected dimensions.~~

82. (currently amended) The semiconductor package of claim 78 wherein the first ~~polymer~~ member and the second ~~polymer~~ member comprise a cured B-stage epoxy and a filler.